GOVERNMENT OF INDIA
MINISTRY OF ELECTRONICS AND INFORMATION TECHNOLOGY
RAJYA SABHA
UNSTARRED QUESTION NO. 3250
TO BE ANSWERED ON 20.03.2026

EMPLOYMENT GENERATED IN ELECTRONICS MANUFACTURING SECTOR

3250 #. SHRI NEERAJ DANGI:

Will the Minister of ELECTRONICS AND INFORMATION TECHNOLOGY be pleased to state:

(a) the number of direct and indirect employment opportunities generated in the electronics manufacturing sector during the last three years;
(b) the new markets identified by Government to promote electronics exports and the policy measures proposed to attract foreign investment in the sector; and
(c) whether any timeline has been fixed for establishment of semiconductor fabrication units in the country, if so, the details thereof?

ANSWER

MINISTER OF STATE FOR ELECTRONICS AND INFORMATION TECHNOLOGY
(SHRI JITIN PRASADA)

(a) to (c): Driven by the Hon'ble Prime Minister's vision of Make in India and Atmanirbhar Bharat, Government of India has taken several policy initiatives to develop a complete ecosystem of electronics manufacturing.

India has witnessed a remarkable growth in electronics manufacturing in the last decade, which is evident from the table below:

#	**2014-15**	**2024-25**	**Remarks**
Production of electronics goods (in ₹)	~1.9 Lakh crore	~11.3 Lakh crore	Increased 6 times
Export of electronics goods (in ₹)	~0.38 Lakh crore	~3.3 Lakh crore	Increased 8 times
Production of mobile phones (in ₹)	~0.18 Lakh crore	~5.5 Lakh crore	Increased 28 times
Export of mobile phones in (in ₹)	~0.01 Lakh crore	~ 2 Lakh crore	Increased 127 times

Mobile Phone imported (units)	75% of the total demand	0.02% of the total demand	

This transformation has been made possible by various initiatives taken by the Government in the last 11 years to attract foreign investments, strengthen export competitiveness and position India as a global electronics manufacturing hub.

Some of these are as follows:

- Production-linked incentives (PLI) for large-scale electronics manufacturing
- Production-linked incentives (PLI) for IT Hardware
- Scheme for Promotion of Manufacturing of Electronic Components and Semiconductors (SPECS)
- Electronics Manufacturing Clusters (EMC and EMC 2.0) Scheme
- Electronics Manufacturing Component Scheme (ECMS)
- Public Procurement (Preference to Make in India) Order 2017 to prioritize domestically manufactured products in public procurement
- Reforms in taxation including rationalization of tariff structure including, exemption on basic custom duty on capital goods, etc.

Electronics Exports

The electronics exports have witnessed an eightfold increase from around ₹0.38 Lakh crores in FY 2014-15 to ₹ 3.3 Lakh crores in FY 2024-25.

Smartphone has emerged as the topmost category in the exported goods in Calendar Year 2025, which can be seen from the table below:

#	HS Code	Item	Export value (in USD) during CY (Jan’ 2025 to Dec’ 2025)
1	85171300	Smartphones	30.13 Billion
2	27101944	Automotive diesel fuel, not containing biodiesel, conforming to standard is 1460	16.34 Billion
3	71023910	Diamond (other than industrial diamond) cut or otherwise worked but not mounted or set	12.47 Billion

(Source: Directorate General of Commercial Intelligence and Statistics)

India is expanding electronics exports by focusing on key global markets such as the USA, UAE, Netherlands, UK, and Italy, which together accounted for a significant share (63.5%) of the total electronics exports in 2024–25, which can be seen from the table below:

#	Country	Exports Value in FY 2024 -25 (in ₹ Cr)
1	United States of America (USA)	1,24,605 (~USD 14.6 Bn.)
2	United Arab Emirates (UAE)	31,256 (~USD 3.6)
3	Netherlands	24,235 (~USD 2.8 Bn.)
4	United Kingdom (UK)	15,666 (~USD 1.8 Bn.)
5	Italy	12,043 (~USD 1.4 Bn.)

(Source: MoC's trade intelligence and analytics portal)

Employment Generation

The growth of the electronics manufacturing sector has led to substantial employment generation. As per industry estimates, it supports around 25 lakh jobs, including direct and indirect employment.

Out of this, the mobile phone manufacturing sector alone supports around 12 lakh jobs, across manufacturing, logistics, supply chains and allied services.

Apart from this, the Government is implementing flagship schemes to further boost employment by attracting investments.

Under the India Semiconductor Mission (ISM), 10 semiconductor units are under construction. As a foundational industry, semiconductor manufacturing is expected to have a cascading impact on employment generation across the supply chain and allied sectors, leading to significant indirect job creation.

Similarly, under Electronics Component Manufacturing Scheme (ECMS), 249 applications have been received for components, base materials and capital equipments such as PCBs, capacitors, laminates etc.

India Semiconductor Mission

Government has approved 10 Semiconductor manufacturing units under the Semicon India Programme. The Details of the projects are provided in the **Annexure- I.**

Out of this, commercial production from 1 unit and pilot production from 3 units has already started.

Tata Electronics Private Limited (TEPL) is setting up a Semiconductor Fab facility in Gujarat with an investment of ₹91,526 crores. It will have the capacity to produce 50,000 wafer starts per month (WSPM) by 2029.

SiCSem Private Limited is also setting up India's first end-to-end Silicon Carbide (SiC) semiconductor fab in Odisha at an investment of ₹2,067 crores. It will have the capacity of 60,000 SiC wafers and packaging of 9.6 crore units annually.

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<u>**Annexure- I**</u>

Details of approved semiconductor manufacturing projects:

1. Micron Technology Inc. is establishing semiconductor manufacturing facility in Gujarat with an investment of ₹22,516 crore. Micron's facility in India will enable assembly and test manufacturing for both DRAM and NAND products and address demand from domestic and international markets. The production capacity is around 14 million units per week.
2. Tata Electronics Private Limited (TEPL) is establishing semiconductor manufacturing facility in Gujarat with an investment of ₹91,526 crore. The fab facility will be set up in technology partnership with PSMC, Taiwan. The production capacity of the project would be around 50,000 wafer starts per month (WSPM).
3. Tata Electronics Private Limited (TEPL) is establishing semiconductor manufacturing facility in Assam with an investment of ₹27,120 crores. The facility will use indigenous semiconductor packaging technologies with a production capacity of 48 million units per day.
4. CG Power and Industrial Solutions Limited is establishing semiconductor manufacturing facility in Gujarat with an investment of ₹7,584 crore. The facility will be set up as a joint venture partnership with Renesas Electronics America Inc., USA, and STARS Microelectronic, Thailand. The Technology would be provided for this facility by Renesas Electronics Corporation, Japan and STARS Microelectronic, Thailand. The production capacity would be around 15.07 million units per day.
5. Kaynes Technology India Limited (KTIL) is establishing semiconductor manufacturing facility in Gujarat with an investment of ₹3,307 crores for Wire bond Interconnect, Substrate Based Packages. The Technology would be provided by ISO Technology Sdn. Bhd. and AOI Electronics Co. Ltd. (AOI). The facility will have the capacity to produce more than 6.33 million chips per day.
6. Vama Sundari Investments (Delhi) Private Limited (VSIPL) is establishing semiconductor manufacturing facility in Uttar Pradesh with an investment of ₹ 3,706 crores for display driver ICs (DDIC) using Gold (Au) Bump technology along with chip probing facilities and die processing services. The Technology would be provided by Hon Hai, Taiwan. The facility will be set up as a joint venture partnership between VSIPL and Foxconn, India. The production capacity would be around 20K wafers per month/36 million chips per month.
7. 3D Glass Solutions Inc. (3DGS) is establishing semiconductor manufacturing facility in Odisha with an investment of ₹1,943 crores. The plant will handle the assembly of packaged products such as Flip Chip Ball Grid Array (FCBGA) assembly, Radio Frequency System in Package (RF SiP), Antenna in Package System in Package (AiP SiP), glass interposers with passives and silicon bridges and 3D Heterogeneous Integration (3DHI) modules. The Proposed installed capacity for glass panel substrate production, assembly and 3DHI is around 5800 panels per month, 4.20 million units per month, and 1100 units per months respectively.
8. SiCSem Private Limited is establishing semiconductor manufacturing facility in Odisha with an investment of ₹2,066 crores. The facility will be set up in technology partnership with Clas-SiC Wafer Fab Ltd. for SiC fab and Continental Device India Pvt. Ltd. for packaging. The production capacity is 5,000 wafers/month, and the packaging capacity is 8 million units/month.
9. Continental Device India Private Limited (CDIL) is expanding its semiconductor manufacturing facility in Punjab, with an investment of ₹117 crores. The facility will manufacture high-power discrete semiconductor devices such as MOSFETs, IGBTs, Schottky Bypass Diodes, and

transistors, both in Silicon and Silicon Carbide. The production capacity will be around 158.38 million units/annum.

10. Advanced System in Package Technologies Private Limited (ASIP) is establishing semiconductor manufacturing facility in Andhra Pradesh, with an investment of ₹480 crores. The facility will be set up in technology partnership with APACT Co. Ltd, South Korea. The production capacity of the facility would be around 96 million units/annum.

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